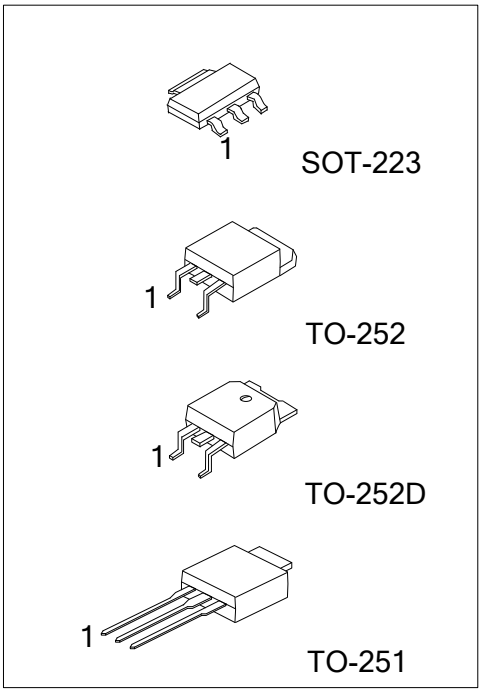
7A, 100V N-CHANNEL POWER MOSFET



■ DESCRIPTION

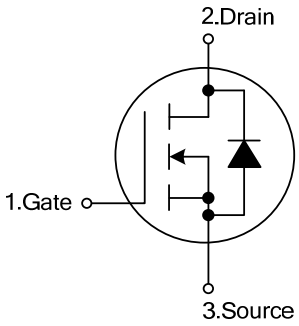
The UTC **7N10** is an N-Channel enhancement mode power MOSFET, providing customers with excellent switching performance and minimum on-state resistance. The UTC **7N10** uses planar stripe and DMOS technology to provide perfect quality. This device can also withstand high energy pulse in the avalanche and the commutation mode.

The UTC **7N10** is generally applied in low voltage applications, such as DC motor controls, audio amplifiers and high efficiency switching DC/DC converters.

■ FEATURES

* $R_{DS(ON)}$ < 0.35Ω @ V_{GS} =10V, I_D =3.5A
* Fast Switching
* Improved dv/dt Capability

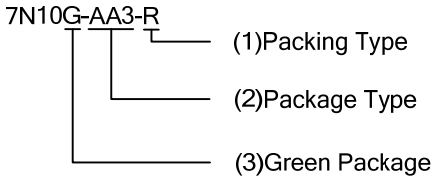
■ SYMBOL



■ ORDERING INFORMATION

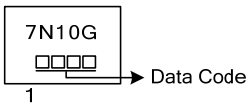
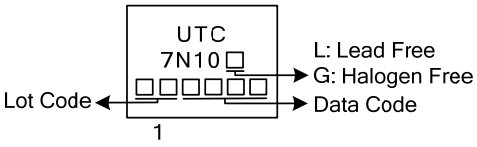
Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
-	7N10G-AA3-R	SOT-223	G	D	S	Tape Reel
7N10L-TM3-T	7N10G-TM3-T	TO-251	G	D	S	Tube
7N10L-TN3-R	7N10G-TN3-R	TO-252	G	D	S	Tape Reel
7N10L-TND-R	7N10G-TND-R	TO-252D	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source



(1) R: Tape Reel, T: Tube
(2) AA3: SOT-223, TM3: TO-251, TN3: TO-252
TND: TO-252D
(3) G: Halogen Free and Lead Free, L: Lead Free

■ MARKING

SOT-223	TO-251 / TO-252 / TO-252D
	

■ ABSOLUTE MAXIMUM RATINGS (T_A =25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain -Source Voltage		V_{DSS}	100	V
Gate-Source Voltage		V_{GSS}	±25	V
Continuous Drain Current	T_C =25°C	I_D	7	A
	T_C = 70°C	I_D	6.8	A
Pulsed Drain Current (Note 2)		I_{DM}	16	A
Avalanche Current (Note 2)		I_{AR}	7	A
Repetitive Avalanche Energy (Note 2)		E_{AR}	0.2	mJ
Single Pulsed Avalanche Energy (Note 3)		E_{AS}	50	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	6.0	V/ns
Power Dissipation	SOT-223	P_D	2.0	W
	TO-251/TO-252 TO-252D		2.5	
Derate above 25°C	SOT-223		0.016	W/°C
	TO-251/TO-252 TO-252D		0.02	
Operating Junction Temperature		T_J	-55 ~ +150	°C
Storage Temperature		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating : Pulse width limited by maximum junction temperature
3. L =26mH, I_{AS} =1.7A, V_{DD} =25V, R_G =25Ω Starting T_J =25°C
4. I_{SD} ≤7.3A, di/dt ≤300A/μs, V_{DD} ≤BV_{DSS}, Starting T_J =25°C

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	SOT-223	θ_{JA}	62.5	°C/W
	TO-251/TO-252 TO-252D		50	
Junction to Case	SOT-223	θ_{JC}	12	°C/W
	TO-251/TO-252 TO-252D		7.5	

Note: When mounted on the minimum pad size recommended (PCB Mount)

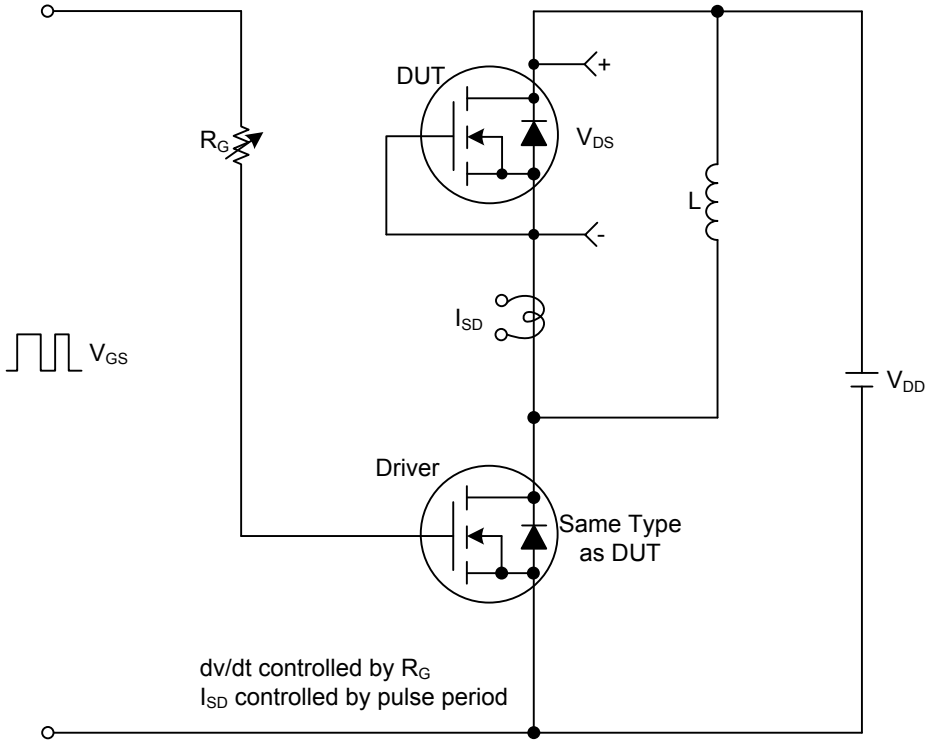
■ ELECTRICAL CHARACTERISTICS (T_C =25°C, unless otherwise specified)

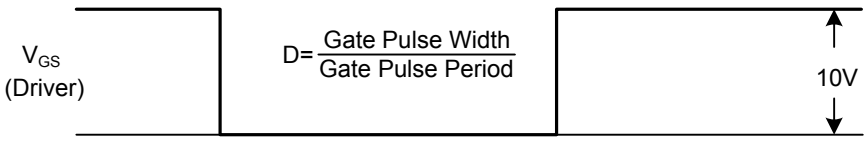
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS} =0V, I_D =250μA	100			V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to 25°C, I_D =250μA		0.1		V/°C
Drain-Source Leakage Current	I_{DSS}	V_{DS} =100V, V_{GS} =0V			1	μA
		V_{DS} =80V, T_C =125°C			10	μA
Gate-Source Leakage Current	I_{GSS}	V_{GS} =±25V, V_{DS} =0V			±100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	V_{DS} = V_{GS}, I_D =250μA	2.0		4.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	V_{GS} =10V, I_D =3.5A		0.144	0.35	Ω
Forward Transconductance	g_{FS}	V_{DS} =40V, I_D =0.85A (Note 1)		1.85		S
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	V_{DS} =25V, V_{GS}=0V, f=1.0MHz		380	450	pF
Output Capacitance	C_{OSS}			70	85	pF
Reverse Transfer Capacitance	C_{RSS}			11	15	pF
SWITCHING PARAMETERS						
Total Gate Charge	Q_G	V_{GS}=10V, V_{DS}=50V, I_D=1.3A (Note 1,2)		14.3		nC
Gate Source Charge	Q_{GS}			4.2		nC
Gate Drain Charge	Q_{GD}			3.2		nC
Turn-ON Delay Time	$t_{D(ON)}$	V_{DD}=30V, I_D=0.5A, R_G=25Ω (Note 1,2)		30	38	ns
Turn-ON Rise Time	t_R			40	50	ns
Turn-OFF Delay Time	$t_{D(OFF)}$			80	90	ns
Turn-OFF Fall-Time	t_F			35	40	ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Maximum Continuous Drain-Source Diode Forward Current	I_S				7	A
Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}				16	A
Drain-Source Diode Forward Voltage	V_{SD}	I_S =7A, V_{GS} =0V			1.5	V
Reverse Recovery Time	t_{rr}	V_{GS}=0V, I_S=7.3A, di_F/dt=100A/μs		70		ns
Reverse Recovery Charge	Q_{RR}			150		nC

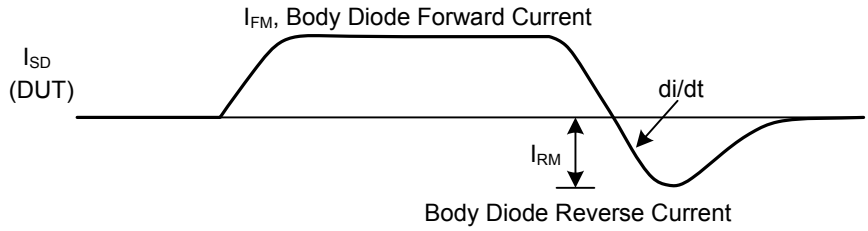
Notes: 1. Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%
2. Essentially independent of operating temperature

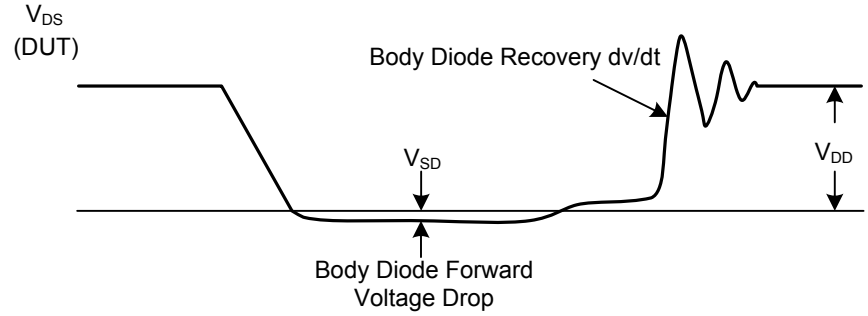
■ TEST CIRCUITS AND WAVEFORMS

Peak Diode Recovery dv/dt Test Circuit & Waveforms

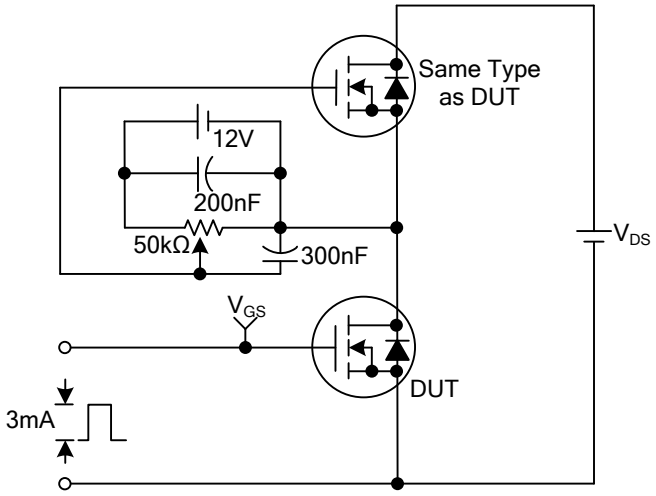




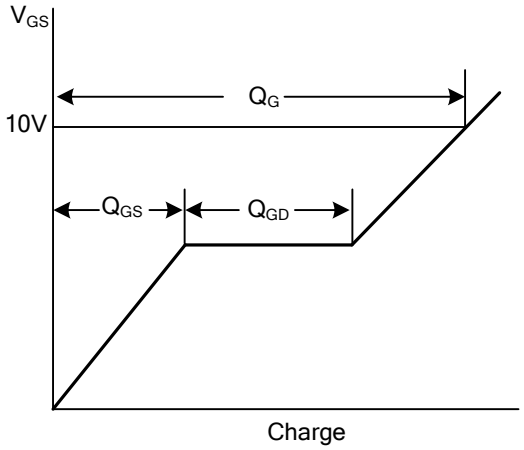




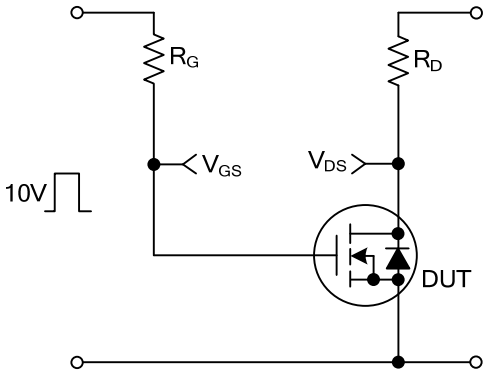
■ TEST CIRCUITS AND WAVEFORMS (Cont.)



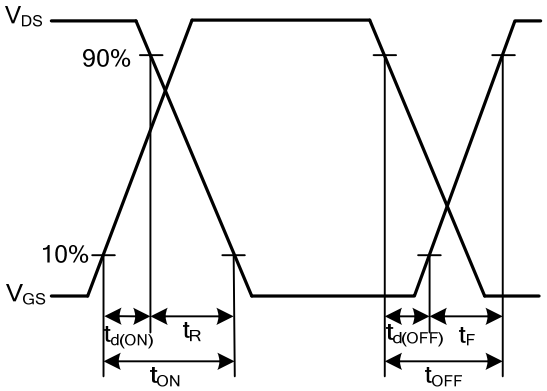
Gate Charge Test Circuit



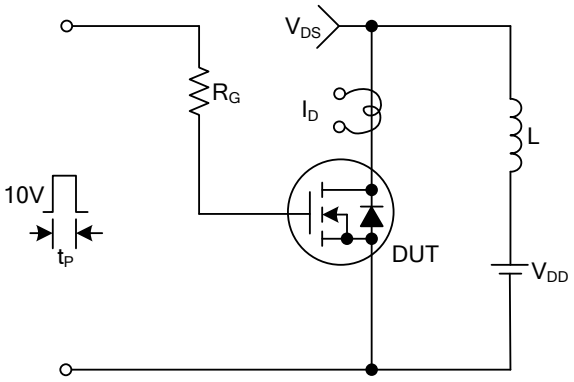
Gate Charge Waveforms



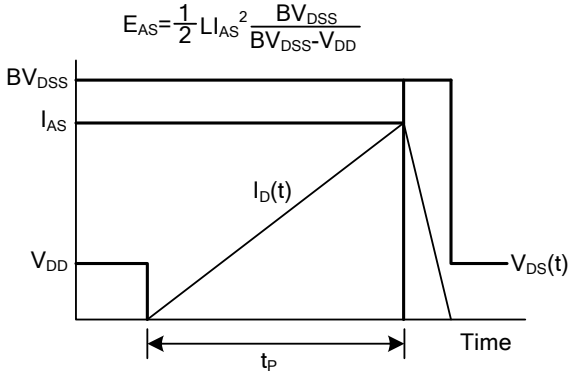
Resistive Switching Test Circuit



Resistive Switching Waveforms



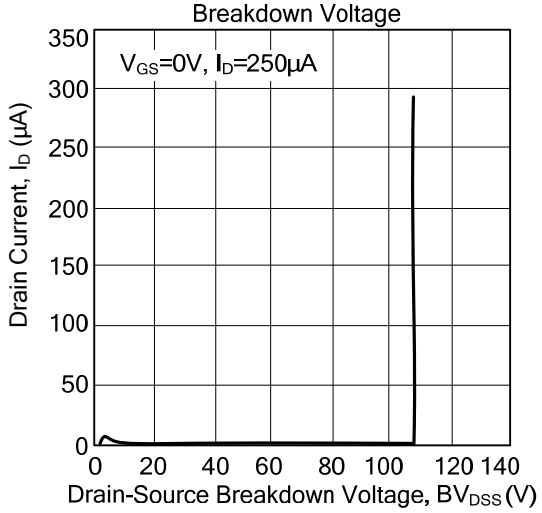
Unclamped Inductive Switching Test Circuit



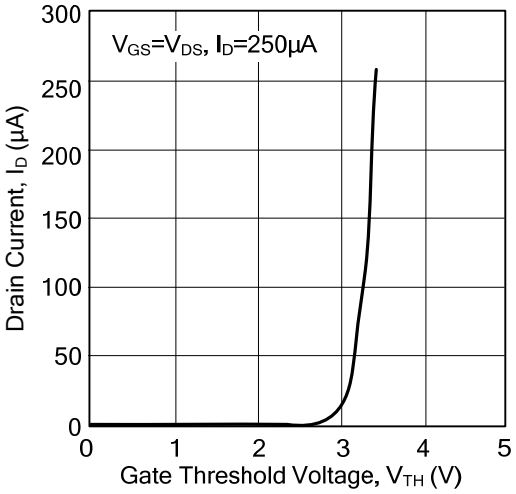
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

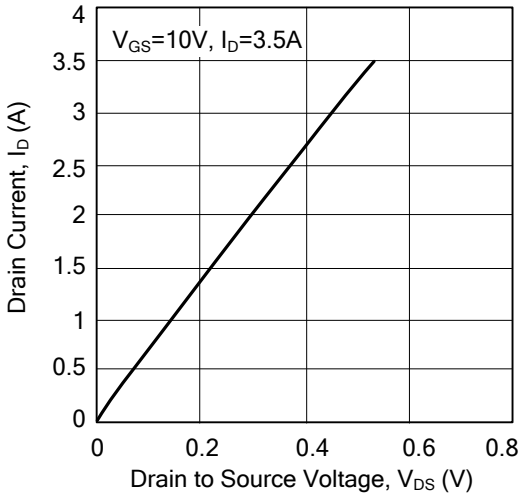
Drain Current vs. Drain-Source Breakdown Voltage



Drain Current vs. Gate Threshold Voltage



Drain-Source On-State Resistance Characteristics



7N10 SOA Chart (TO-252, T_C=25°C)